

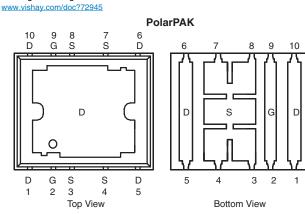
RoHS

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
		I _D (A) ^a				
V _{DS} (V)	R _{DS(on)} (Ω) ^e	Silicon Limit	Package Limit	Q _g (Typ.)		
30	0.0019 at V _{GS} = 10 V	202	60	50 nC		
30	0.0026 at V_{GS} = 4.5 V	173	60	30110		

Package Drawing

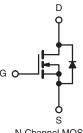


FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Gen II Power MOSFET
 - COMPLIANT Ultra Low Thermal Resistance Using Top-HALOGEN Exposed PolarPAK[®] Package for Double-Sided FREE Cooling Available
- Leadframe-Based New Encapsulated Package - Die Not Exposed
- Same Layout Regardless of Die Size
- Low Q_{gd}/\dot{Q}_{gs} Ratio Helps Prevent Shoot-Through 100 % R_g and UIS Tested
- Compliant to RoHS directive 2002/95/EC

APPLICATIONS

- VRM
- DC/DC Conversion: Low-Side
- Synchronous Rectification



N-Channel MOSFET For Related Documents www.vishay.com/ppg?72985

Top surface is connected to pins 1, 5, 6, and 10

Ordering Information: SiE802DF-T1-E3 (Lead (Pb)-free) SiE802DF-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		202 (Silicon Limit)		
	10 = 25 0		60 ^a (Package Limit)		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _C = 70 °C	I _D	60 ^a		
	T _A = 25 °C		42.7 ^{b, c}		
	T _A = 70 °C		34.2 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	100		
Continuous Source-Drain Diode Current	T _C = 25 °C		60 ^a		
Continuous Source-Drain Diode Current	T _A = 25 °C	IS	4.3 ^{b, c}		
Single Pulse Avalanche Current L = 0.1 mH Avalanche Energy L = 0.1 mH		I _{AS}	50		
		E _{AS}	125	mJ	
	T _C = 25 °C		125		
Maximum Power Dissipation	T _C = 70 °C	P _D	80	w	
	T _A = 25 °C	'D	5.2 ^{b, c}		
	T _A = 70 °C		3.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera	ature) ^{d, e}		260		

a. Package limited is 60 A.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. See Solder Profile (www.vishay.com/doc?73257). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

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THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	20	24	
Maximum Junction-to-Case (Drain Top)	Steady State	R _{thJC} (Drain)	0.8	1	°C/W
Maximum Junction-to-Case (Source) ^{a, c}	Sleady State	R _{thJC} (Source)	2.2	2.7	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Maximum under Steady State conditions is 68 °C/W.

c. Measured at source pin (on the side of the package).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	•		•	•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		32.2		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \ \mu A$		- 6.4			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.5	2.2	2.7	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V$, $V_{GS} = 10 V$	25			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 23.6 A		0.0016	0.0019	Ω	
		V _{GS} = 4.5 V, I _D = 21.3 A		0.0021	0.0026		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 23.6 A		156		S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			7000		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		1200			
Reverse Transfer Capacitance	C _{rss}	—		500			
Total Gate Charge	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 23.6 \text{ A}$		105	160	nC	
		V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 23.6 A		50	75		
Gate-Source Charge	Q _{gs}			21			
Gate-Drain Charge	Q _{gd}			14			
Gate Resistance	R _g	f = 1 MHz		1.1	1.65	Ω	
Turn-On Delay Time	t _{d(on)}			45	70		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		195	300	- ns	
Turn-Off Delay Time	t _{d(off)}	${ m I}_{ m D}\cong$ 10 A, ${ m V}_{ m GEN}$ = 4.5 V, ${ m R}_{ m g}$ = 1 Ω		45	70		
Fall Time	t _f			20	30		
Turn-On Delay Time	t _{d(on)}			25	40		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		20	30		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		65	100		
Fall Time	t _f	_		10	15		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			60	A	
Pulse Diode Forward Current ^a	I _{SM}				100	~	
Body Diode Voltage	V _{SD}	I _S = 10 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			55	85	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 10 A, dl/dt = 100 A/μs, T _{.1} = 25 °C		66	105	nC	
Reverse Recovery Fall Time	t _a	$F = 10 \text{ A}, \text{ u/ul} = 100 \text{ A/}\mu\text{s}, 1\text{ J} = 25 \text{ C}$		25		ns	
Reverse Recovery Rise Time	t _b			30			

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

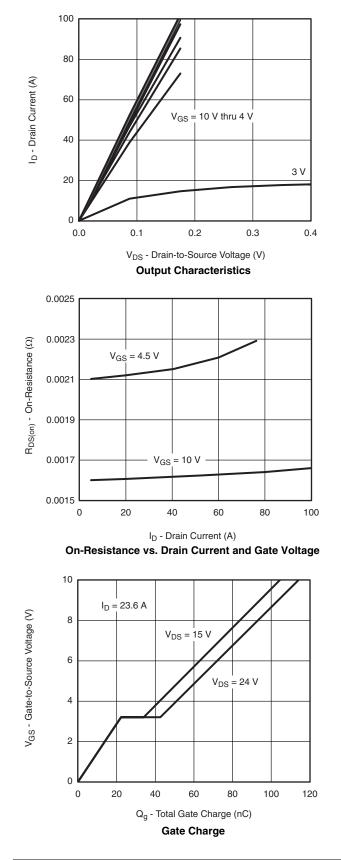
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

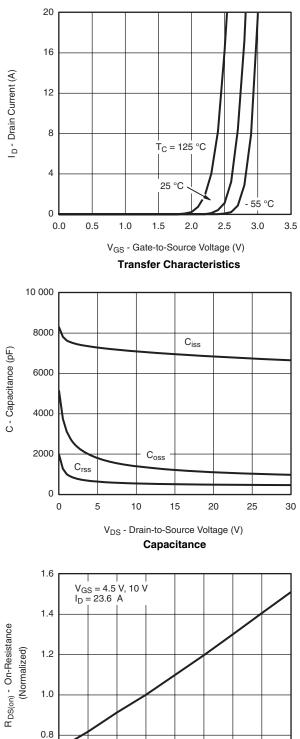


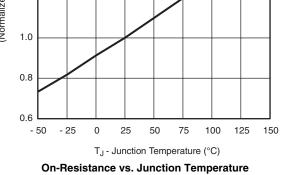
SiE802DF

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





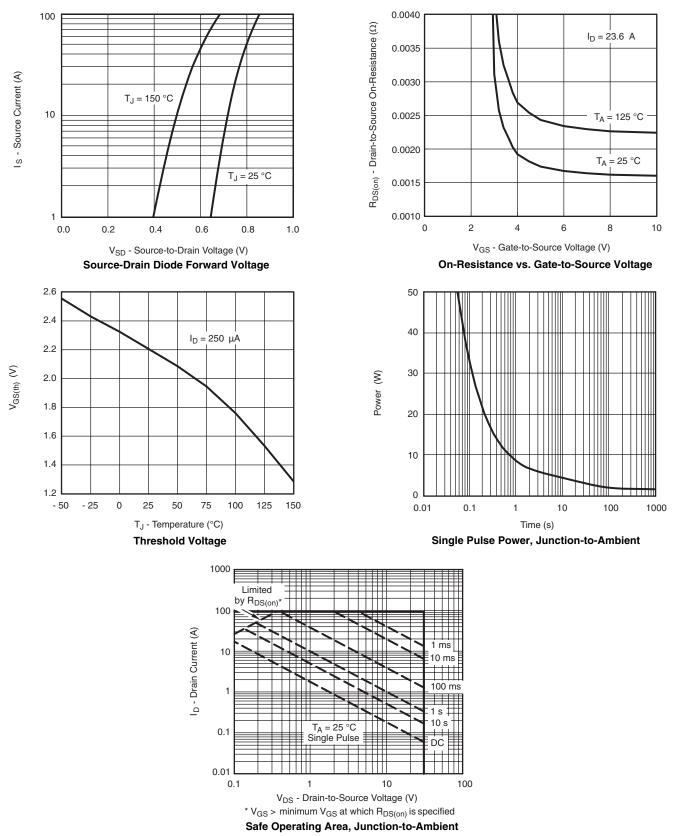


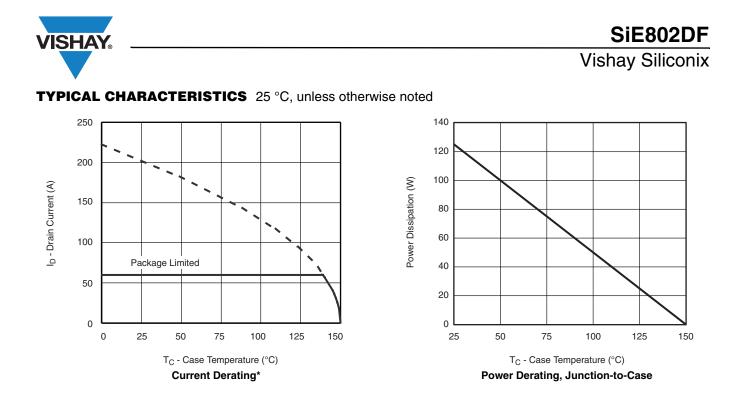
SiE802DF



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





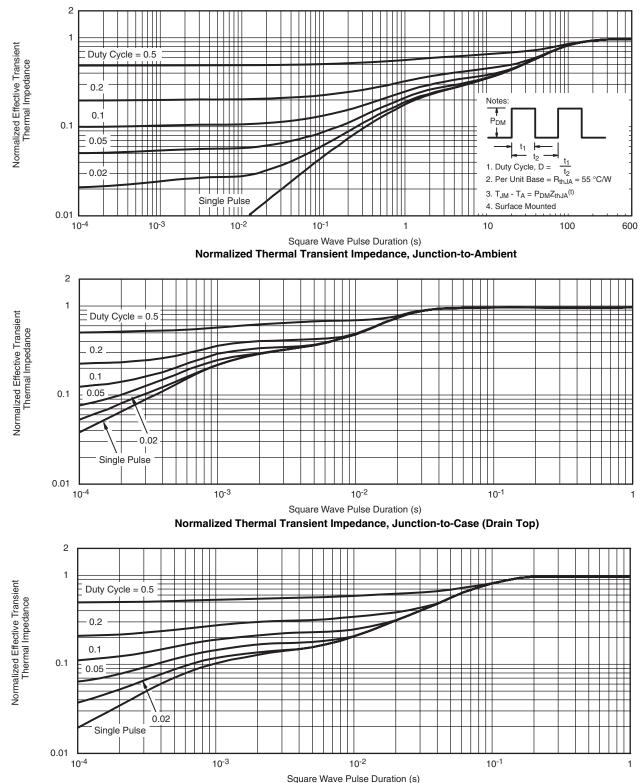
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

SiE802DF

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Source

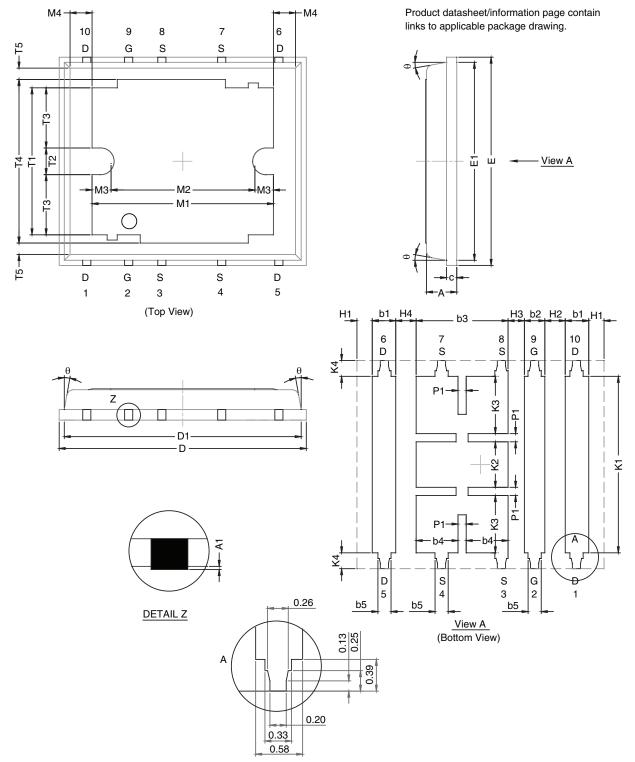
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg?72985</u>.



Package Information

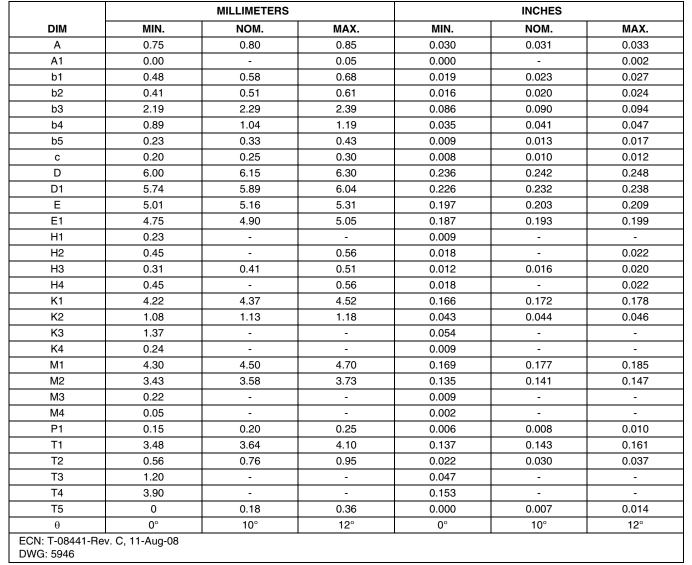
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POLARPAK™ OPTION L



Package Information

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Notes

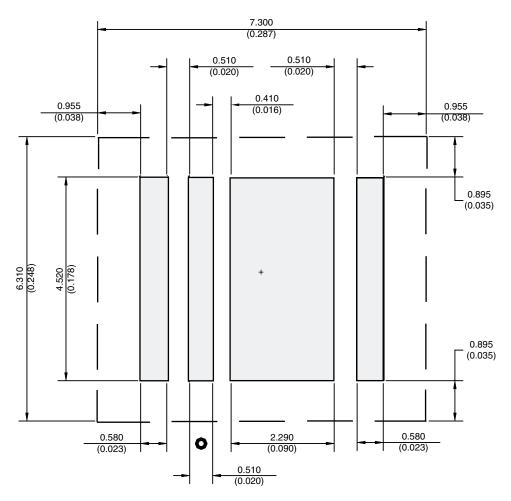
Millimeters govern over inches.



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RECOMMENDED MINIMUM PADS FOR PolarPAK® Option L and S



Recommended Minimum for PolarPAK Option L and S Dimensions in mm/(Inches) No External Traces within Broken Lines Dot indicates Gate Pin (Part Marking)

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